

**$V_{DRM}$**  = 5200 V  
 **$I_{T(AV)M}$**  = 440 A  
 **$I_{T(RMS)}$**  = 690 A  
 **$I_{TSM}$**  =  $5 \times 10^3$  A  
 **$V_{TO}$**  = 1.2 V  
 **$r_T$**  = 1.6 mW

# Phase Control Thyristor

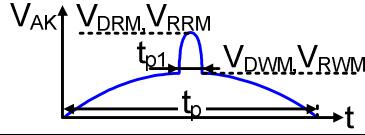
**5STP 04D5200**

Doc. No. 5SYA1026-05 May 07

- Patented free-floating silicon technology
- Low on-state and switching losses
- Designed for traction, energy and industrial applications
- Optimum power handling capability
- Interdigitated amplifying gate

## Blocking

Maximum rated values <sup>1)</sup>

Parameter	Symbol	Conditions	5STP 04D5200	Unit
Max. surge peak forward and reverse blocking voltage	$V_{DSM}, V_{RSM}$	$t_p = 10$ ms, $f = 5$ Hz $T_{vj} = 5 \dots 125^\circ\text{C}$ , Note 1	5200	V
Max repetitive peak forward and reverse blocking voltage	$V_{DRM}, V_{RRM}$	$f = 50$ Hz, $t_p = 10$ ms, $t_{p1} = 250$ $\mu\text{s}$ , $T_{vj} = 5 \dots 125^\circ\text{C}$ , Note 1, Note 2	5200	V
Max crest working forward and reverse voltages	$V_{DWM}, V_{RWM}$	$V_{AK}$ 	2600	V
Critical rate of rise of commutating voltage	$dv/dt_{crit}$	Exp. to 2950 V, $T_{vj} = 125^\circ\text{C}$	1000	V/ $\mu\text{s}$

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Forward leakage current	$I_{DRM}$	$V_{DRM}, T_{vj} = 125^\circ\text{C}$			100	mA
Reverse leakage current	$I_{RRM}$	$V_{RRM}, T_{vj} = 125^\circ\text{C}$			100	mA

Note 1: Voltage de-rating factor of 0.11% per  $^\circ\text{C}$  is applicable for  $T_{vj}$  below  $+5^\circ\text{C}$

Note 2: Recommended minimum ratio of  $V_{DRM} / V_{DWM}$  or  $V_{RRM} / V_{RWM} = 2$ . See App. Note 5SYA 2051.

## Mechanical data

Maximum rated values <sup>1)</sup>

Parameter	Symbol	Conditions	min	typ	max	Unit
Mounting force	$F_M$		8	10	12	kN
Acceleration	a	Device unclamped			50	$\text{m/s}^2$
Acceleration	a	Device clamped			100	$\text{m/s}^2$

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Weight	m				0.3	kg
Housing thickness	H	$F_M = 10$ kN, $T_a = 25^\circ\text{C}$	26.2		26.8	mm
Surface creepage distance	$D_S$		25			mm
Air strike distance	$D_a$		14			mm

1) Maximum rated values indicate limits beyond which damage to the device may occur

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## On-state

### Maximum rated values <sup>1)</sup>

Parameter	Symbol	Conditions	min	typ	max	Unit
Average on-state current	$I_{T(AV)M}$	Half sine wave, $T_c = 70^\circ C$			440	A
RMS on-state current	$I_{T(RMS)}$				690	A
Peak non-repetitive surge current	$I_{TSM}$	$t_p = 10 \text{ ms}, T_{vj} = 125^\circ C, \text{sine wave}$ $\text{after surge: } V_D = V_R = 0 \text{ V}$			$5 \times 10^3$	A
Limiting load integral	$I^2t$				$125 \times 10^3$	$A^2\text{s}$
Peak non-repetitive surge current	$I_{TSM}$	$t_p = 8.3 \text{ ms}, T_{vj} = 125^\circ C, \text{sine wave}$ $\text{after surge: } V_D = V_R = 0 \text{ V}$			$5.4 \times 10^3$	A
Limiting load integral	$I^2t$				$121 \times 10^3$	$A^2\text{s}$

### Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
On-state voltage	$V_T$	$I_T = 500 \text{ A}, T_{vj} = 125^\circ C$			2.25	V
Threshold voltage	$V_{(TO)}$	$I_T = 200 \text{ A} - 1000 \text{ A}, T_{vj} = 125^\circ C$			1.2	V
Slope resistance	$r_T$				1.6	$m\Omega$
Holding current	$I_H$	$T_{vj} = 25^\circ C$			80	$mA$
		$T_{vj} = 125^\circ C$			60	$mA$
Latching current	$I_L$	$T_{vj} = 25^\circ C$			500	$mA$
		$T_{vj} = 125^\circ C$			200	$mA$

## Switching

### Maximum rated values <sup>1)</sup>

Parameter	Symbol	Conditions	min	typ	max	Unit
Critical rate of rise of on-state current	$di/dt_{crit}$	$T_{vj} = 125^\circ C, I_{TRM} = 1500 \text{ A}, f = 50 \text{ Hz}$			100	$A/\mu s$
Critical rate of rise of on-state current	$di/dt_{crit}$	$V_D \leq 2950 \text{ V}, I_{FG} = 2 \text{ A}, t_r = 0.5 \mu s$			1000	$A/\mu s$
Circuit-commutated turn-off time	$t_q$	$T_{vj} = 125^\circ C, I_{TRM} = 2000 \text{ A}, V_R = 200 \text{ V}, di_T/dt = -1.5 \text{ A}/\mu s, V_D \leq 0.67 \cdot V_{DRM}, dv_D/dt = 20 \text{ V}/\mu s$	700			$\mu s$

### Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse recovery charge	$Q_{rr}$	$T_{vj} = 125^\circ C, I_{TRM} = 2000 \text{ A}, V_R = 200 \text{ V}, di_T/dt = -1.5 \text{ A}/\mu s$	800		2000	$\mu As$
Reverse recovery current	$I_{RM}$		25		50	A
Gate turn-on delay time	$t_{gd}$	$T_{vj} = 25^\circ C, V_D = 0.4 \cdot V_{RM}, I_{FG} = 2 \text{ A}, t_r = 0.5 \mu s$			2	$\mu s$

## Triggering

*Maximum rated values<sup>1)</sup>*

Parameter	Symbol	Conditions	min	typ	max	Unit
Peak forward gate voltage	$V_{FGM}$				12	V
Peak forward gate current	$I_{FGM}$				10	A
Peak reverse gate voltage	$V_{RGM}$				10	V
Average gate power loss	$P_{G(AV)}$		see Fig. 9			W

*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Gate-trigger voltage	$V_{GT}$	$T_{vj} = 25^\circ C$			2.6	V
Gate-trigger current	$I_{GT}$	$T_{vj} = 25^\circ C$			400	mA
Gate non-trigger voltage	$V_{GD}$	$V_D = 0.4 \times V_{DRM}, T_{vj} = 125^\circ C$	0.3			V
Gate non-trigger current	$I_{GD}$	$V_D = 0.4 \times V_{DRM}, T_{vj} = 125^\circ C$	10			mA

## Thermal

*Maximum rated values<sup>1)</sup>*

Parameter	Symbol	Conditions	min	typ	max	Unit
Operating junction temperature range	$T_{vj}$				125	°C
Storage temperature range	$T_{stg}$		-40		140	°C

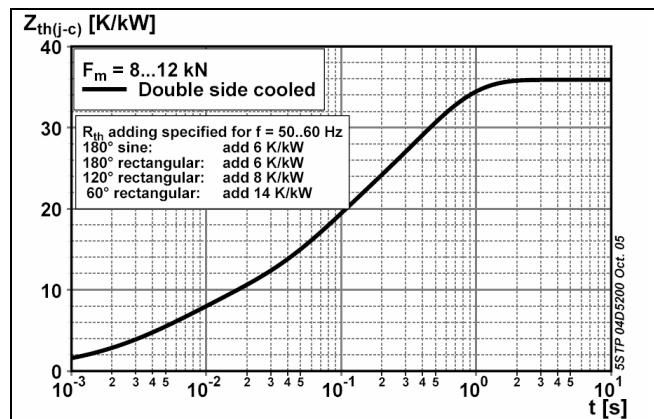
*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Thermal resistance junction to case	$R_{th(j-c)}$	Double-side cooled $F_m = 8...12 \text{ kN}$			36	K/kW
	$R_{th(j-c)A}$	Anode-side cooled $F_m = 8...12 \text{ kN}$			70	K/kW
	$R_{th(j-c)C}$	Cathode-side cooled $F_m = 8...12 \text{ kN}$			74	K/kW
Thermal resistance case to heatsink	$R_{th(c-h)}$	Double-side cooled $F_m = 8...12 \text{ kN}$			7.5	K/kW
	$R_{th(c-h)}$	Single-side cooled $F_m = 8...12 \text{ kN}$			15	K/kW

**Analytical function for transient thermal impedance:**

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

i	1	2	3	4
$R_i(\text{K/kW})$	19.180	9.820	5.450	1.440
$\tau_i(\text{s})$	0.3862	0.0561	0.0058	0.0024



**Fig. 1** Transient thermal impedance (junction-to-case) vs. time

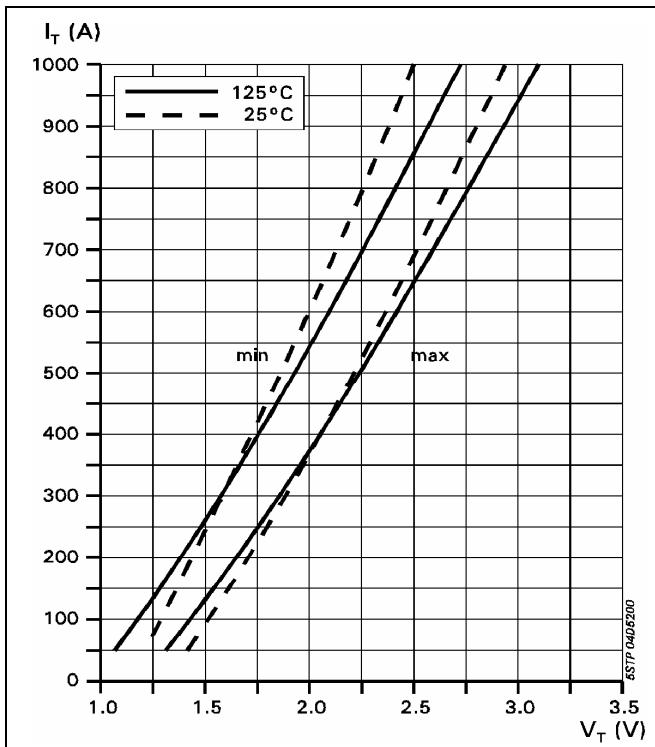


Fig. 2 On-state voltage characteristics

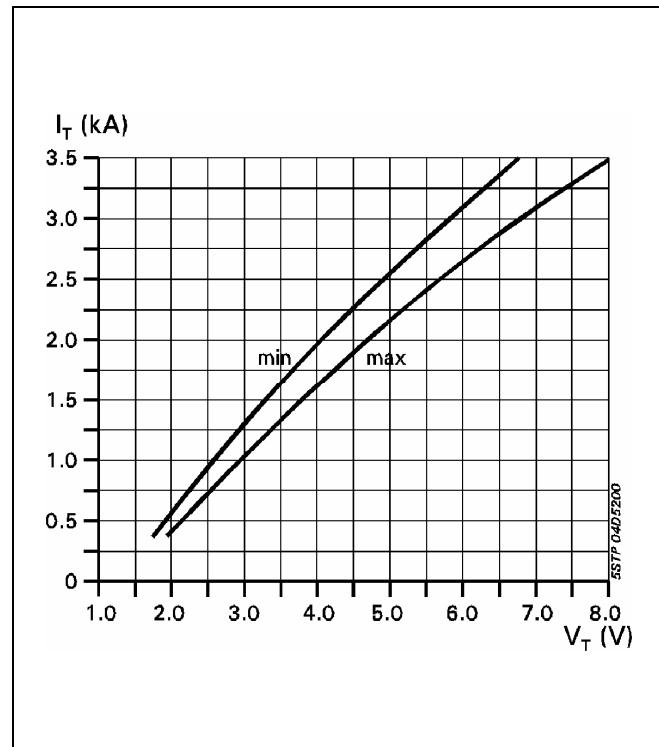
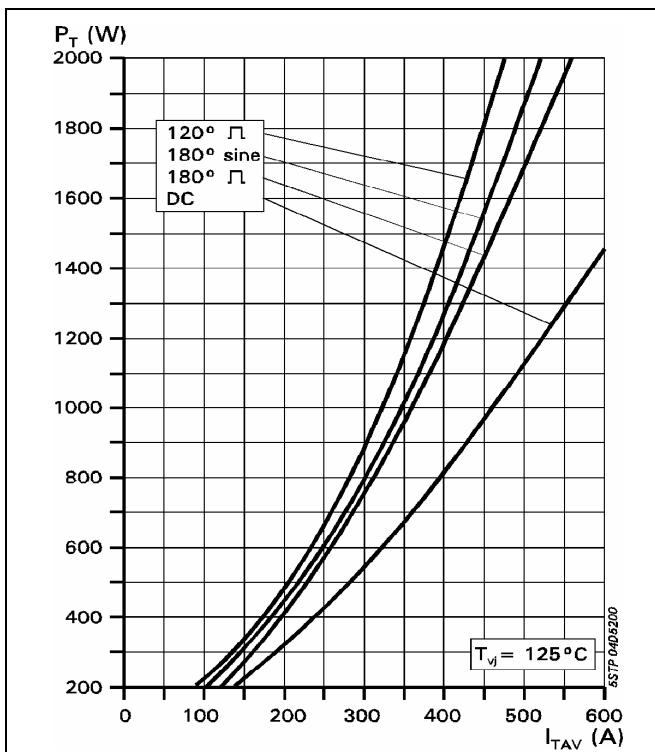
Fig. 3 On-state characteristics,  
 $T_j = 125^\circ\text{C}$ , 10ms half sine

Fig. 4 On-state power dissipation vs. mean on-state current, turn-on losses excluded

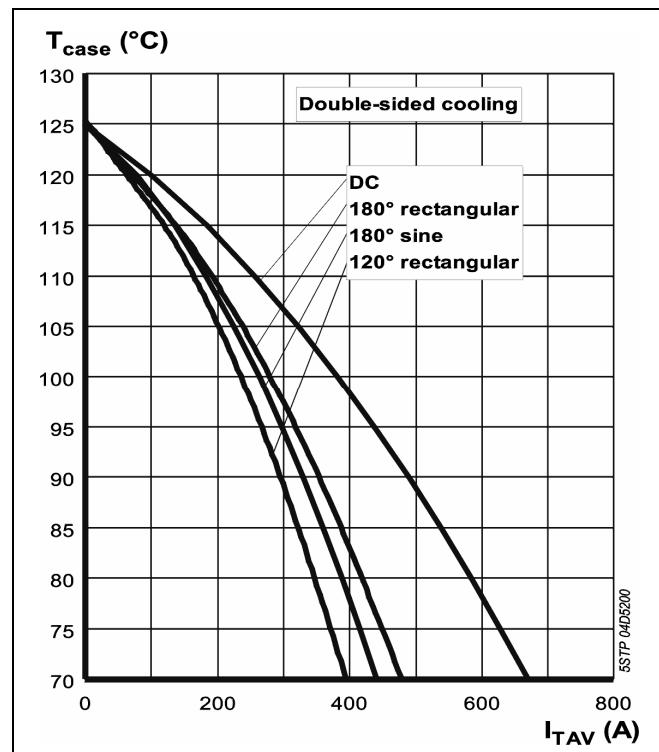
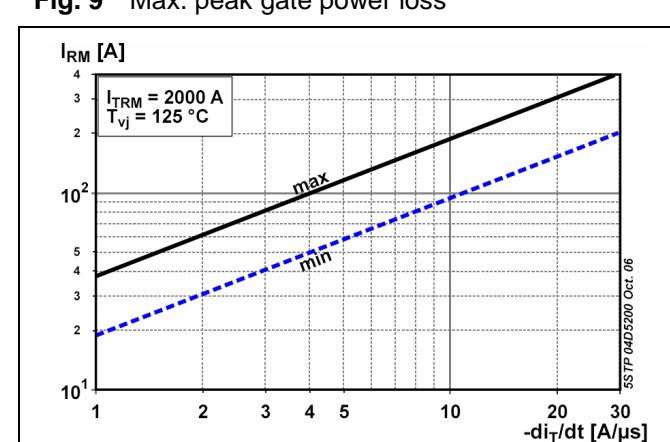
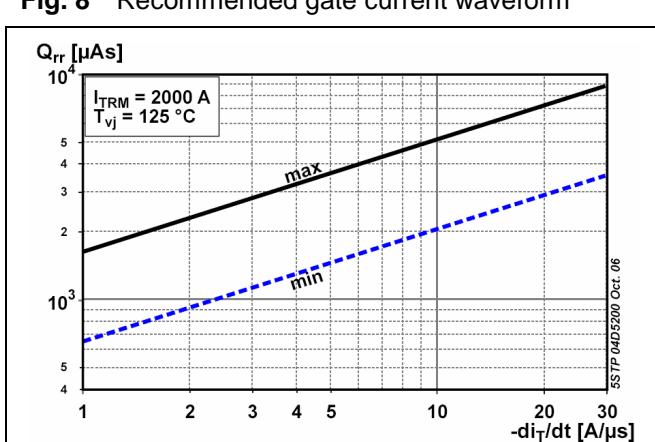
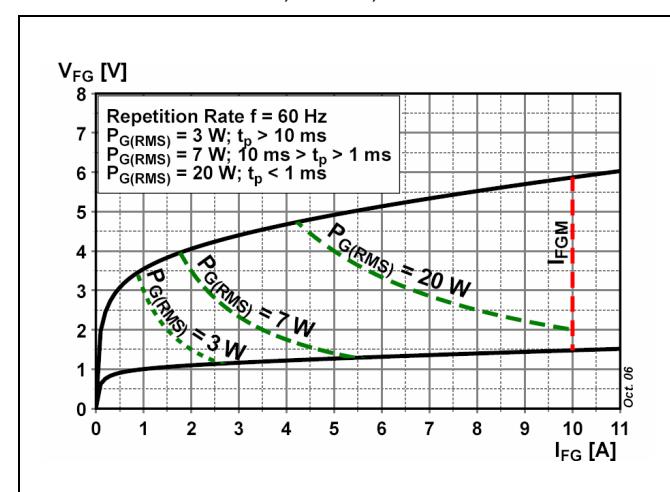
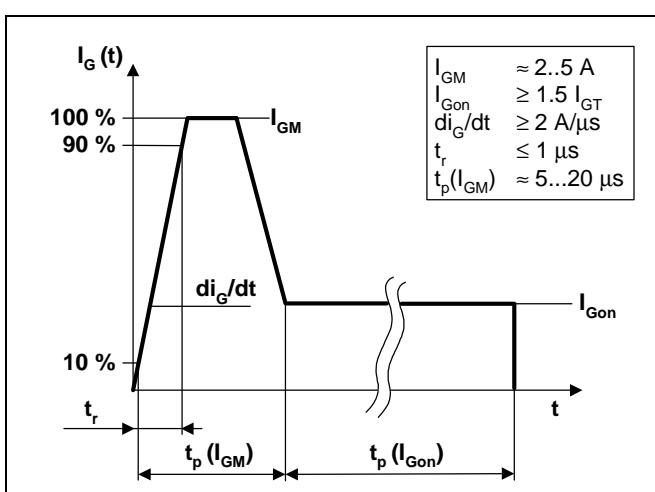
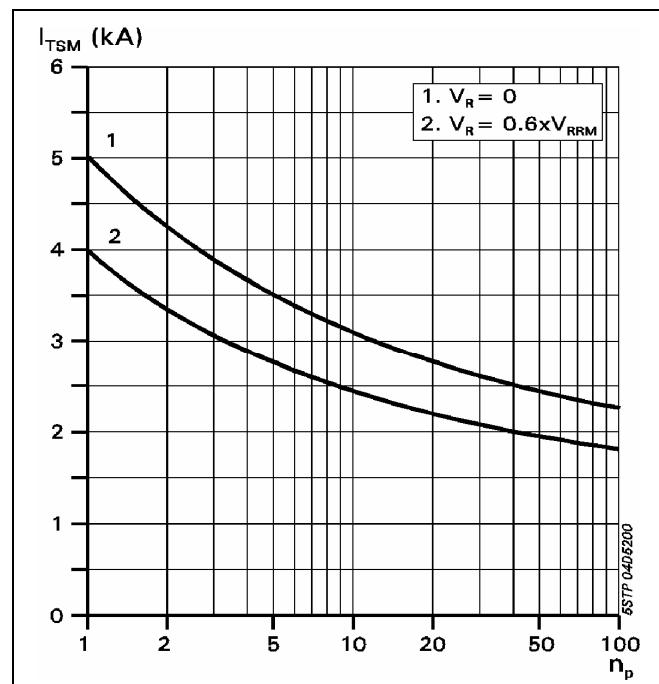
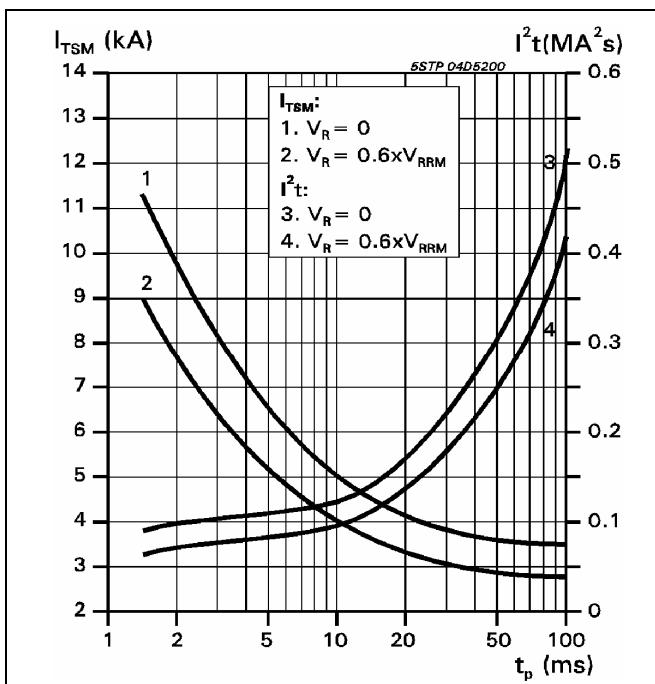


Fig. 5 Max. permissible case temperature vs. mean on-state current, switching losses ignored



## Turn-on and Turn-off losses

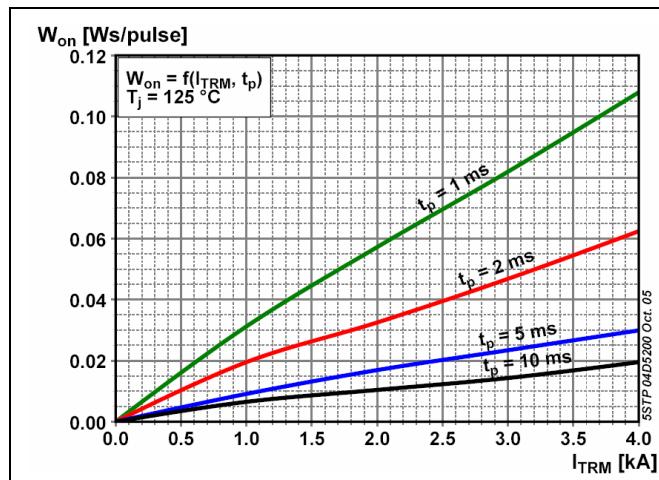


Fig. 12 Turn-on energy, half sinusoidal waves

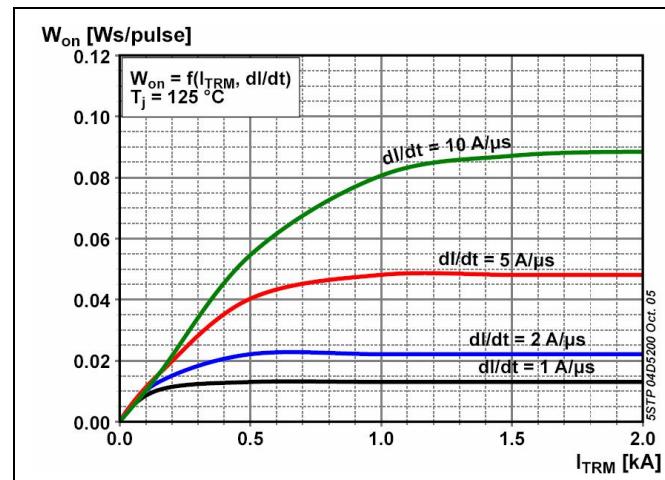


Fig. 13 Turn-on energy, rectangular waves

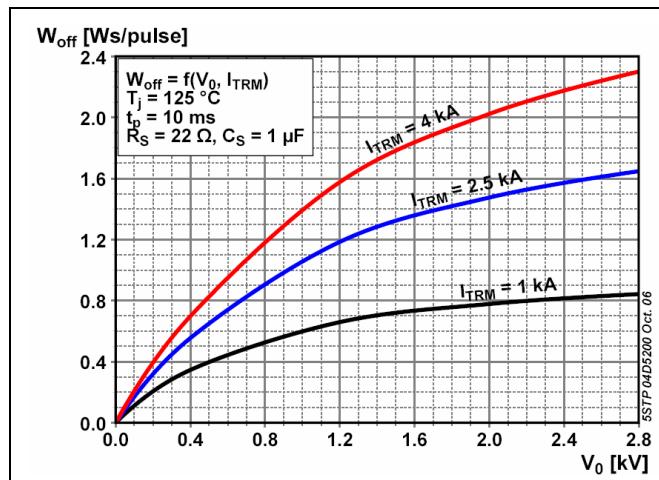


Fig. 14 Turn-off energy, half sinusoidal waves

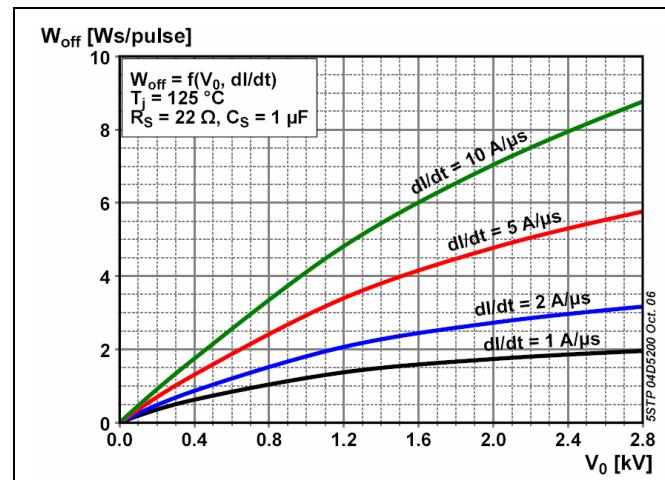


Fig. 15 Turn-off energy, rectangular waves

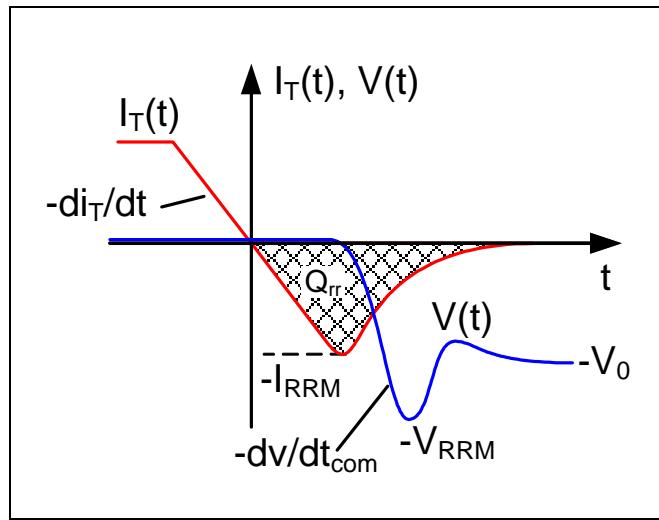


Fig. 16 Current and voltage waveforms at turn-off

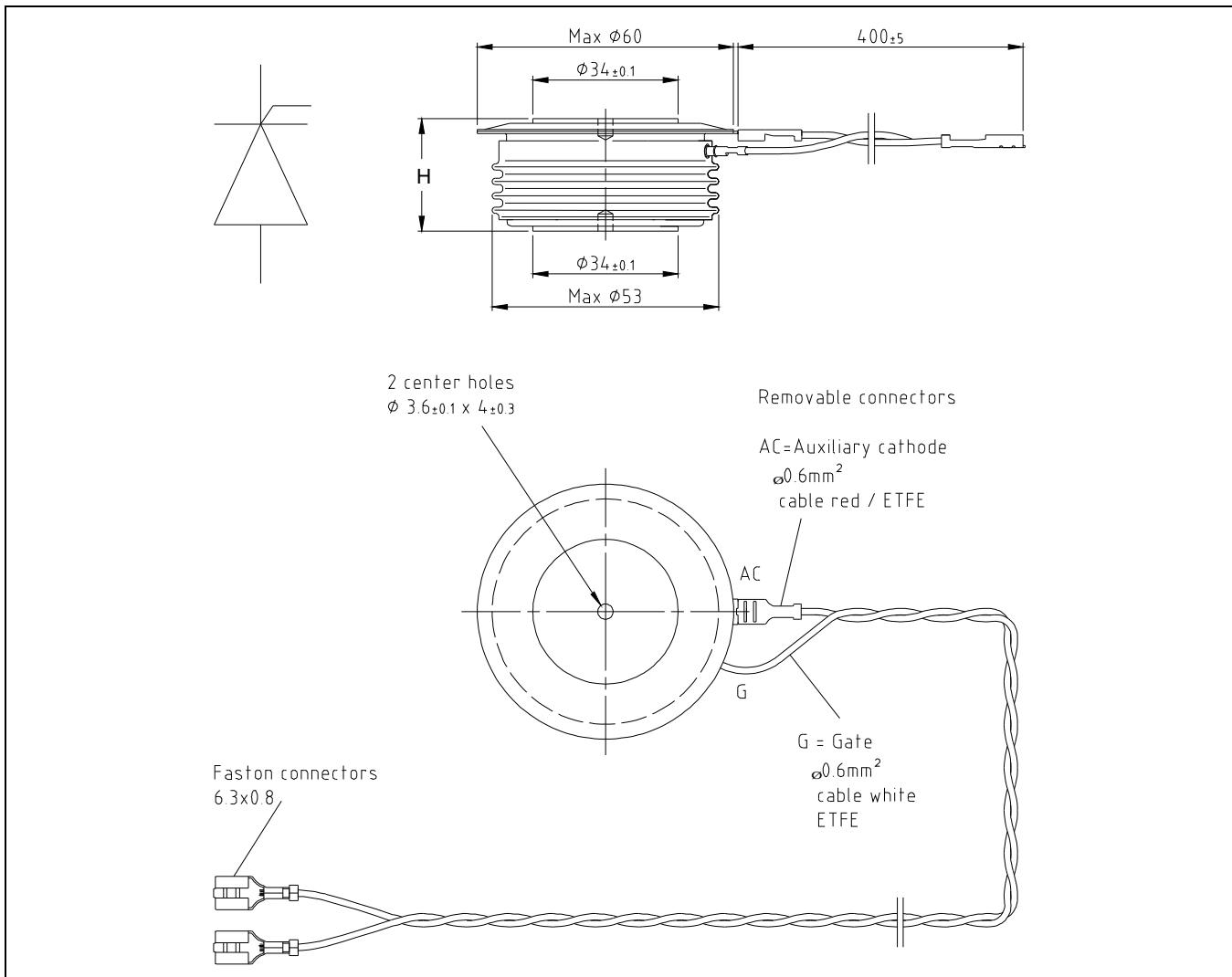
### Total power loss for repetitive waveforms:

$$P_{TOT} = P_T + W_{on} \cdot f + W_{off} \cdot f$$

where

$$P_T = \frac{1}{T} \int_0^T I_T \cdot V_T(I_T) dt$$

Fig. 17 Relationships for power loss



**Fig. 18** Device Outline Drawing

### Related documents:

- |           |                                                                                                                                             |
|-----------|---------------------------------------------------------------------------------------------------------------------------------------------|
| 5SYA 2020 | Design of RC-Snubber for Phase Control Applications                                                                                         |
| 5SYA 2049 | Voltage definitions for phase control thyristors and diodes                                                                                 |
| 5SYA 2051 | Voltage ratings of high power semiconductors                                                                                                |
| 5SYA 2034 | Gate-Drive Recommendations for PCT's                                                                                                        |
| 5SYA 2036 | Recommendations regarding mechanical clamping of Press Pack High Power Semiconductors                                                       |
| 5SZK 9104 | Specification of environmental class for pressure contact diodes, PCTs and GTO, STORAGE available on request, please contact factory        |
| 5SZK 9105 | Specification of environmental class for pressure contact diodes, PCTs and GTO, TRANSPORTATION available on request, please contact factory |

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